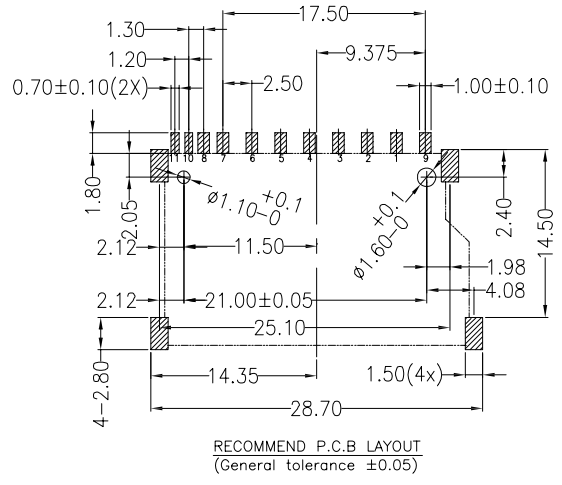
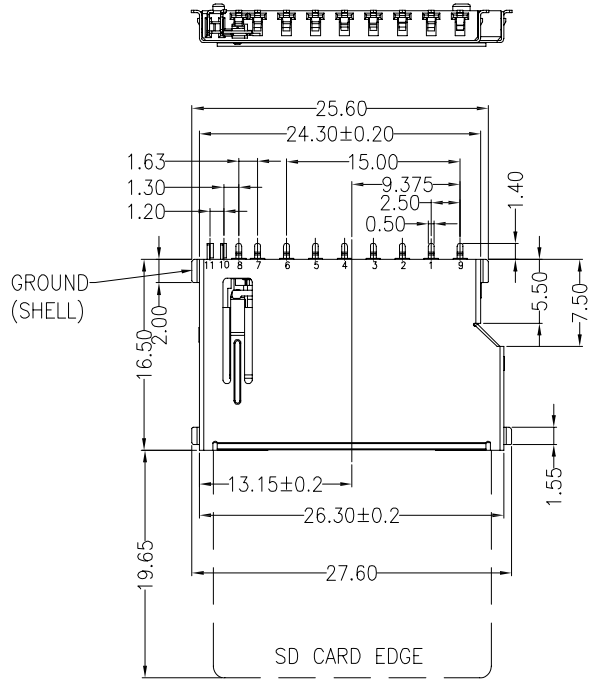
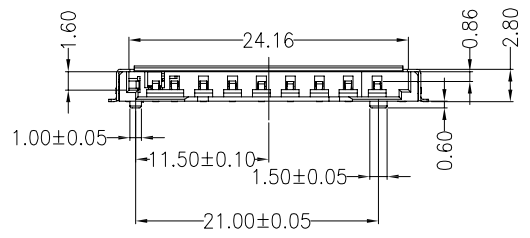
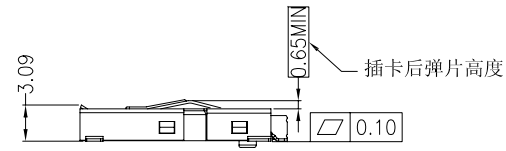


Mark	ECN NO.	DESCRIPTION	DESIGN	Date:
A	—	NEW	—	—

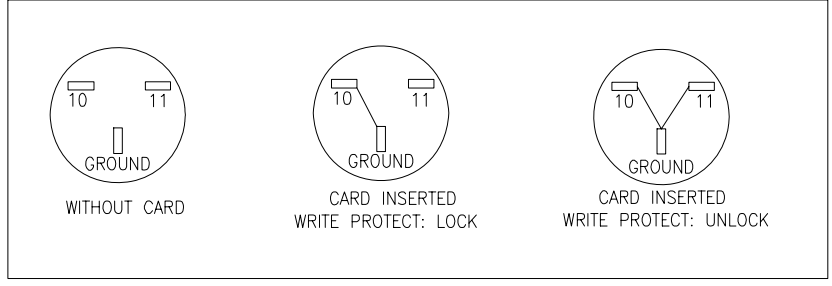


RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

▨ PAD AREA
- - - KEEP OUT AREA



10-CARD DETECT PIN
11-WRITE PROTECT PIN
GROUND(SHELL)-COMMON PIN



SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	
11#	WP	

NOTES:

- MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK
CONTACT: COPPER ALLOY
SHELL: COPPER ALLOY
- PLATING
CONTACT AREA: GOLD PLATED OVER Ni
SOLDER TAIL: 50~100u" MIN Sn PLATED OVER Ni
SHELL SOLDER AREA: NICKEL PLATED
- RATING
CURRENT RATING: 0.5A
VOLTAGE RATING: 250VRMS
OPERATING TEMPERATURE: -25°C~90°C
- SPECIFICATION
CONTACT RESISTANCE: 40 Milliohms
DIELECTIC WITHSTANDING VOLTAGE: 500VAC 1Min.
INSULATION RESISTANCE: 100 Megohms
INSERTION FORCE: 10N Max
SEPARATION FORCE: 2N Min

Tolerance X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 Angle ±2.0°	Model Name: SD卡座 短卡 铜壳 载带包装				Drawing: 彭媛平	
	Model No: WLSD-003B				Checked: 姚世宣	
mm	UNIT:	SCALE:	REVISION:	SHEET	Approved: 李建	
		FULL	A	1/1	Date: 2015.12.01	
	深圳市兴万联电子有限公司 SHENZHEN XINGWANLIAN TECHNOLOGY CO., LTD				DWG NO.	
					FILE: C	